

## Magillem to commercialize STMicroelectronics TLM modelling environment and methodology

**Paris, France, March 19, 2014.** - Magillem, the leading provider of front-end design xml solutions to reduce the global cost of complex SoC and FPGA platforms, is proud to announce that it has signed an OEM agreement with STMicroelectronics to broaden Magillem's ESL offering with the inclusion of ST's TLM modelling environment and methodology.

Thanks to this partnership, Magillem will provide ST's customers and partners with a standard based SystemC TLM infrastructure for the creation and the analysis of Virtual Platforms. The ST technology directly plugs into Magillem's Eclipse-based open design environment to form a comprehensive and interoperable ESL solution. This integrated platform includes automatic code generation that can compile and simulate both HW and SW for all SystemC standards-compliant simulators

*"This cooperation is a new milestone after years of successful collaboration between Magillem and ST. We are excited to make ST's ESL expertise available to other companies and to build a uniquely positioned offering around it,"* stated Cyril Spasevski, Chair and Chief Technology Officer of Magillem.

*"Magillem's vision and its state-of-the-art technology for design-capture automation and content assembly strengthen the ecosystem for our modelling technology and provide an effective complement to the existing offers from the large suppliers: we are introducing to the fast-expanding ESL market a robust virtual platform kit we have developed and successfully used for years,"* said Philippe Magarshack, Executive Vice-President and General Manager, Design Enablement and Services STMicroelectronics.

The new Magillem ESL solution will ensure coherency and consistency among the multiple representations of a system : the RTL platform, the virtual TLM platform, the requirement, and functional specification documents.

### **About Magillem**

Magillem, a member of the ARM Connected Community, a board member of ACCELLERA, has developed an easy to use, IP-XACT based state-of-the-art platform solution to cover **electronic systems design flow** challenges in a context where complexity, interoperability and design re-use are becoming critical issues to **manage design cycle time of SOC**.

Company is headquartered in Paris, France, with offices in Grenoble, Sophia Antipolis, New York, Austin, Dallas, San Jose, (USA), Bristol (UK) and Tokyo (Japan). Magillem has a presence in 12 countries including Israel, Korea, Taiwan, China, Singapore, India..

Customers include the first tier SoC and FPGA manufacturers worldwide. Magillem is a public company traded on the Euronext Market ([FR0010827741](http://www.euronext.com/FR/stocks/FR0010827741)).

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